Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FF 12916 Main Processing Unit(JG634A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on top crashworthy bridge 2, and then remove the top crashworthy bridge 2 from panel 7.
2. Remove shielding finger 3 from panel 7.
3. Remove film 4 from panel 7.
4. Unscrew the screws on heat sink 5, and then remove heat sink 5 from panel 7.
5. Unscrew the screws on pcb 1, and then remove pcb 1.
6. Unscrew the screws on guiding set 6,and then remove guiding set 6 from pcb 1.
7. Remove battery from pcb 1.

(a) Remove conformal coating (if any) and clean work area of any contamination, oxides, adhesives, residues or fluxes.
(b) Install thermal drive desoldering tip handpiece.
(c) Start with tip temperature of approximately 315°C and change as necessary.
(d) Thermal shock tip with damp sponge.
(e) Tin tip with solder. (See Figure 2.)
(f) Lower tip contacting solder connection.
(g) Confirm complete solder melt of contacted lead. (See Figure 3.)
(h) For a flat lead, move lead back and forth; for a round lead, use a circular motion and apply vacuum while continuing lead movement. (See Figures 4&5)
(i) Lift tip from lead, hold vacuum for an additional 3 seconds to clear all molten solder from heater chamber. (See Figure 6.)
(j) Repeat for all solder connections.
(k) Re-tin tip end with solder and return handpiece to its stand.
(l) Lift the component body free of the printed board.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

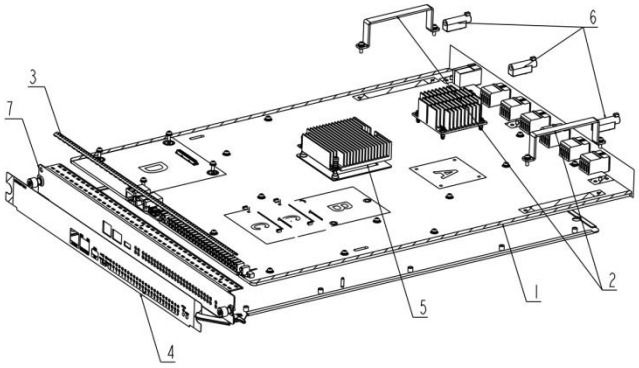

Figure 1 disassembly process

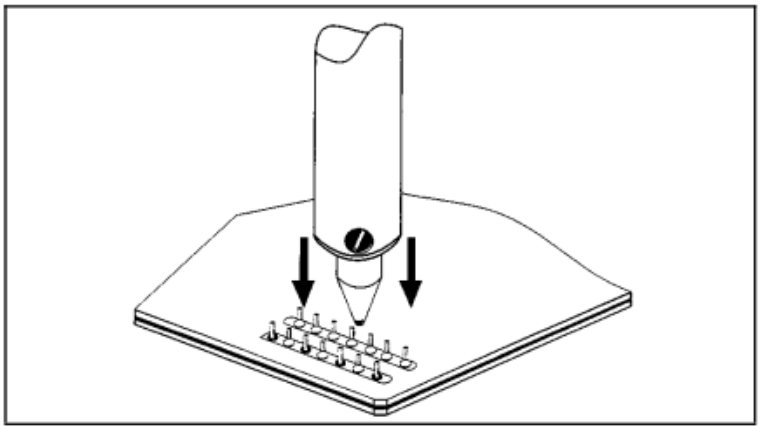

Figure 2 Position Tip

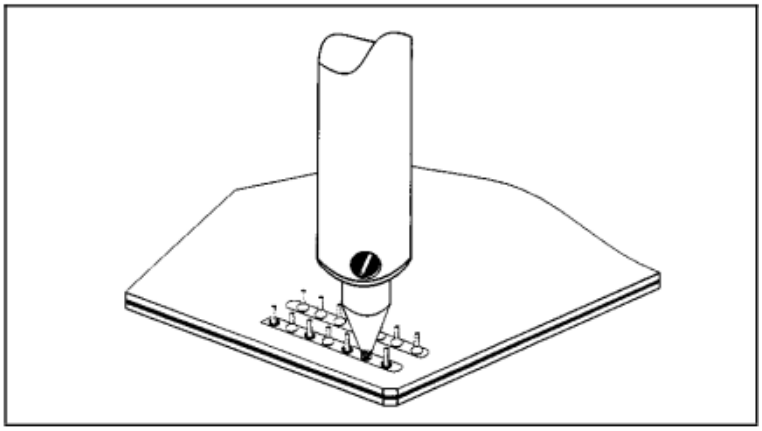

Figure3 Melt Solder

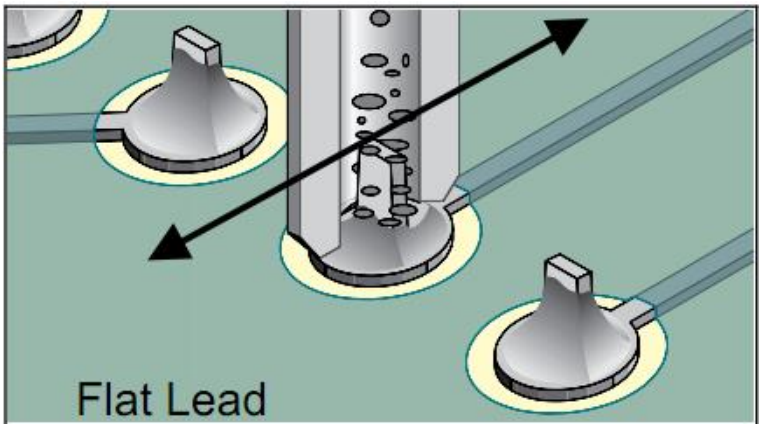

Figure 4 Move Lead & Apply Vacuum

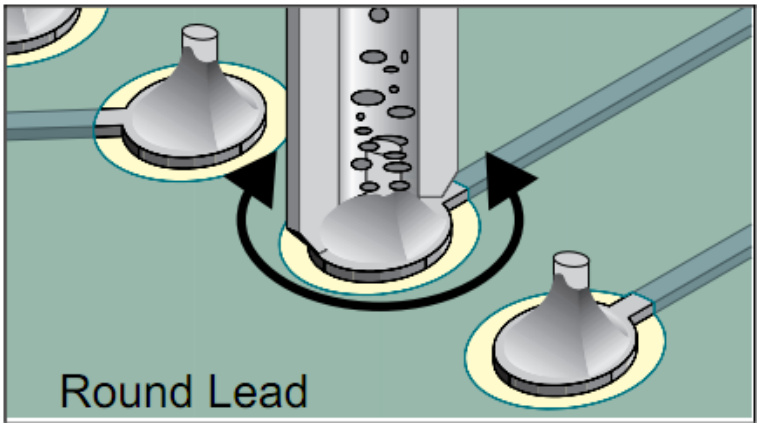

Figure 5 Move Lead & Apply Vacuum

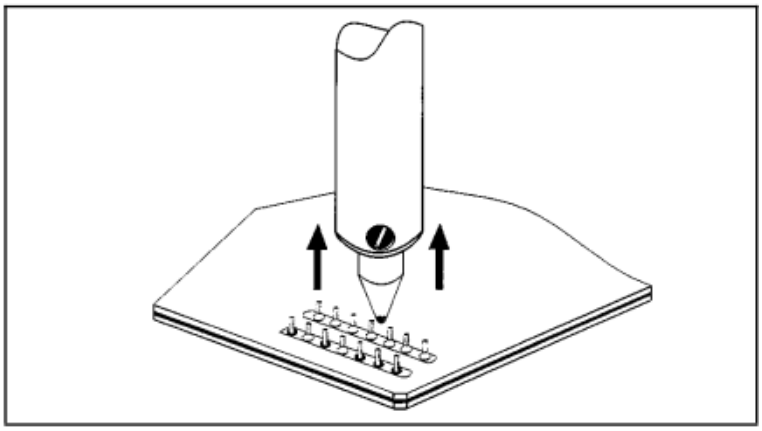

Figure 6 Lift Handpiece

3.3 Material of the facility built

Table 1

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
	1	Complex PWB	1788.7	43%	The surface If PCB is greater than 10 square centimeters	
	2	Fe	48.0	1.168%		Fe recycling
	3	Be-Cu	1.7	0.041%		Cu recycling
	4	PC	4.0	0.097%		Pla recycling
	5	Al, Fe, Pla	162	3.942%		Al&Fe&Pla recycling
	6	Zn	48.0	1.168%		Zn recycling
	7	Fe	2057.6	50.06%		Fe recycling

4. Revised record

Date	Version	Author	Modify content
2013.09.20	V0	Feng Junnan	Initial version